



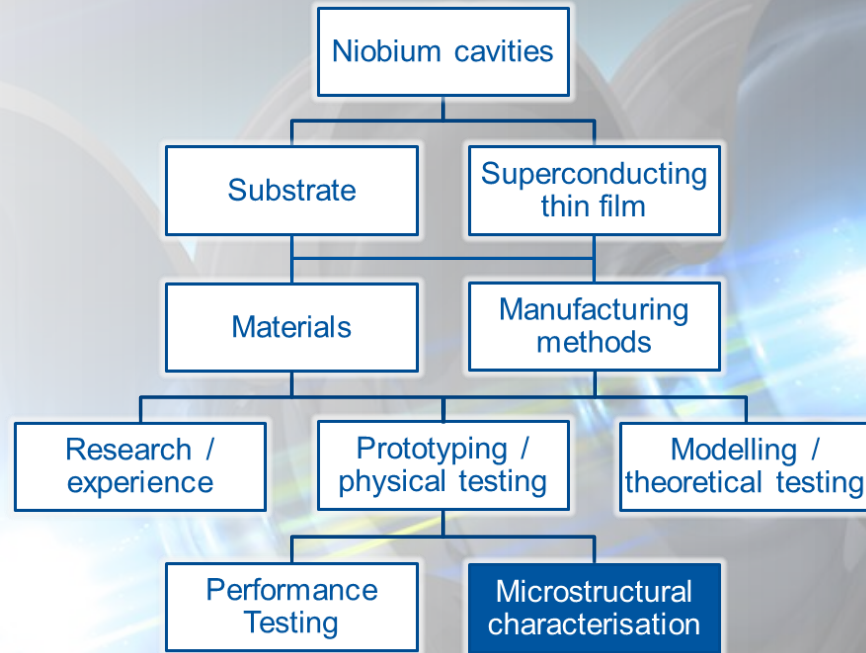
# Micro-to-nanoscale characterisation of SRF cavity coatings for the FCC using advanced FIB microscopy

Alexander Lunt



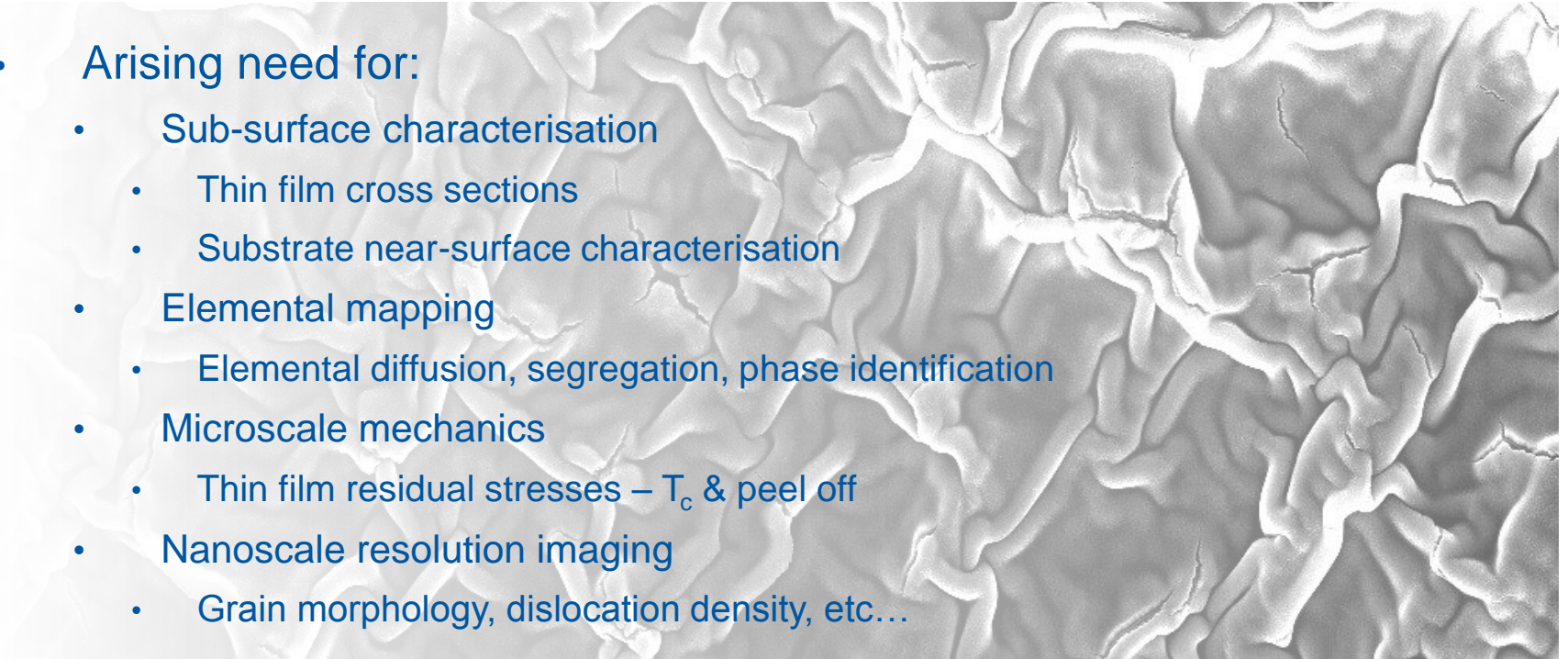
Katsiaryna Ilyina-Brunner, Guillaume Rosaz, Carolina Abajo, Josep Busom-Descarrega, Floriane Leaux & Stefano Sgobba

# SRF Development



# Microstructural characterisation

- Arising need for:
  - Sub-surface characterisation
    - Thin film cross sections
    - Substrate near-surface characterisation
  - Elemental mapping
    - Elemental diffusion, segregation, phase identification
  - Microscale mechanics
    - Thin film residual stresses –  $T_c$  & peel off
  - Nanoscale resolution imaging
    - Grain morphology, dislocation density, etc...



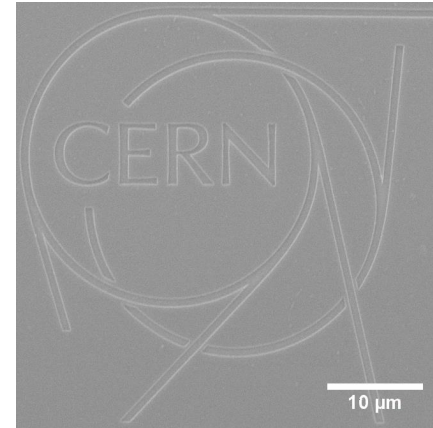
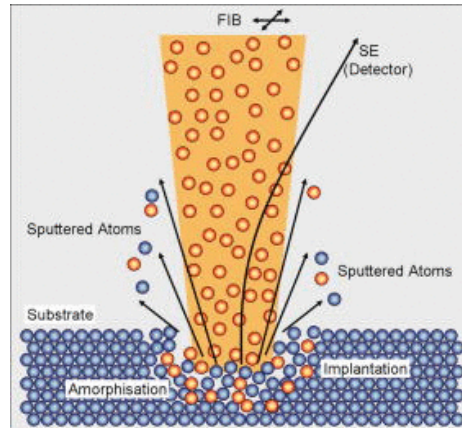
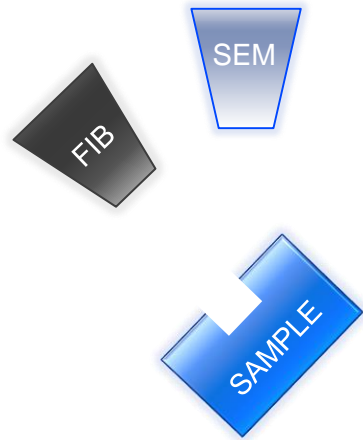
# Focused ion beam (FIB) analysis

- Anticipated arising need
- 2<sup>nd</sup> May 2016
- Zeiss XB540 FIB-SEM
  - Sub nanometre resolution
  - Ga<sup>+</sup> with Pt and C deposition
  - Energy Dispersive Spectroscopy (EDS)
  - Atlas 5
  - Scanning Transmission Electron Microscopy (STEM) detector



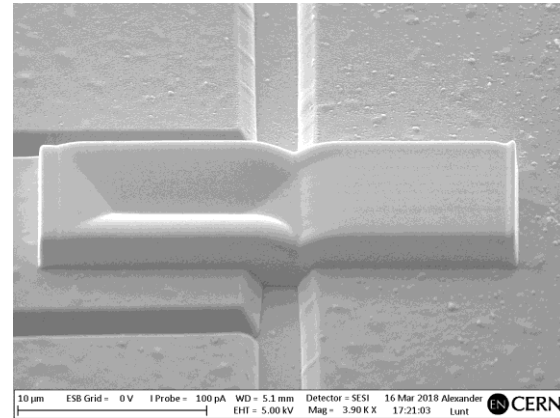
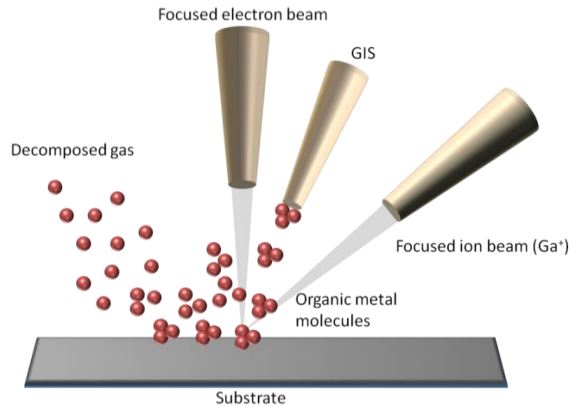
# What is FIB analysis?

- Combined with Scanning Electron Microscope
- Accelerate and focus a beam of ions



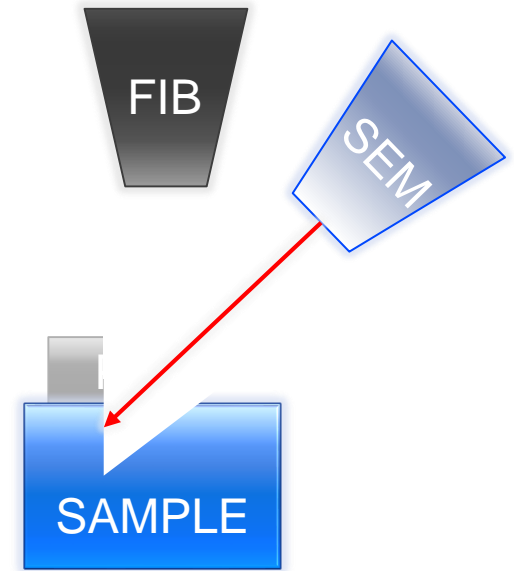
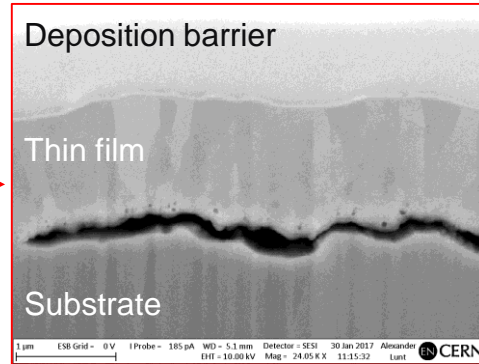
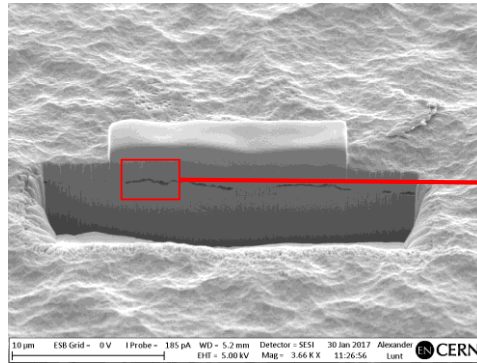
# FIB deposition

- Interaction between precursor and ion beam
- Atomic species of interest deposited



# FIB cross sectional milling

- Pt deposition barrier – protect surface
- FIB milling to produce cross section
- Tilt corrected SEM imaging



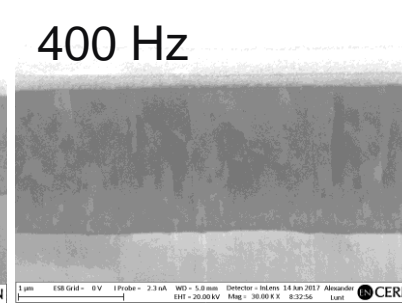
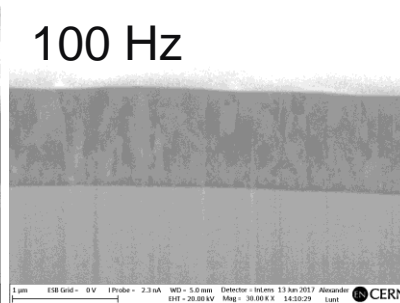
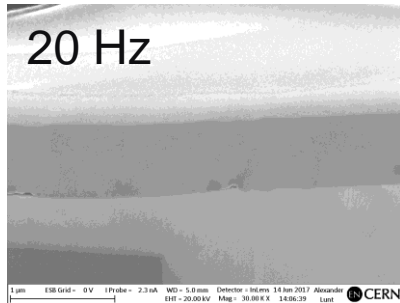


# Example Studies

Katsiaryna Ilyina-Brunner 10:48 Berlage zaal (1.9)  
Guillaume Rosaz 11:06 Berlage zaal (1.9)

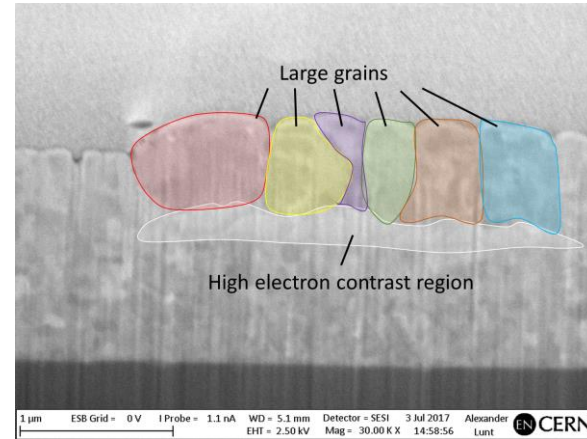
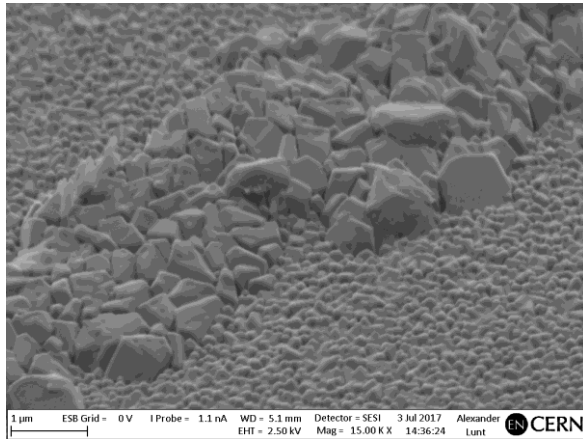
- High-Power Impulse Magnetron Sputtering
  - Pressure, frequency, voltage bias, coating position
- 18 samples studied

Increased frequency = higher coating rate



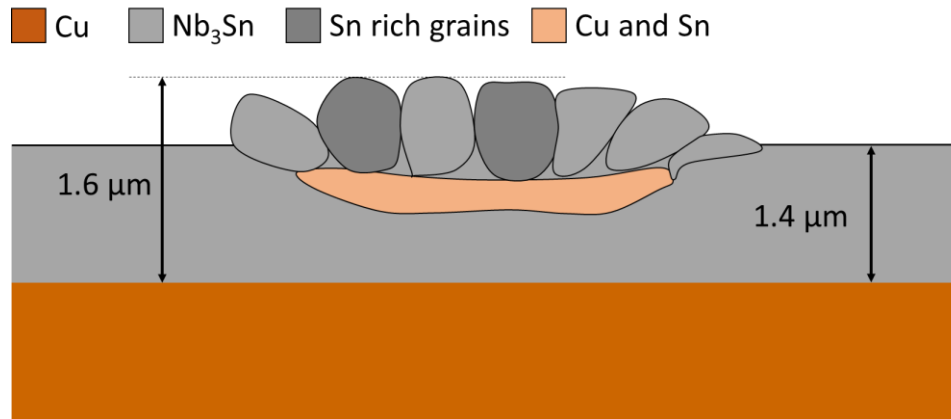
# Surface contamination

- Cu rich deposits observed
- What is the influence on the microstructure?



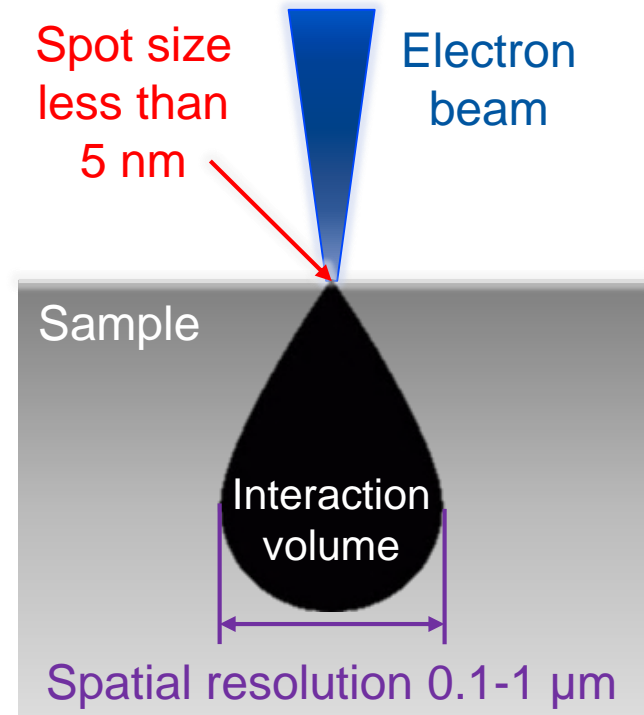
# Surface contamination

- Cu rich deposits observed
- What is the influence on the microstructure?



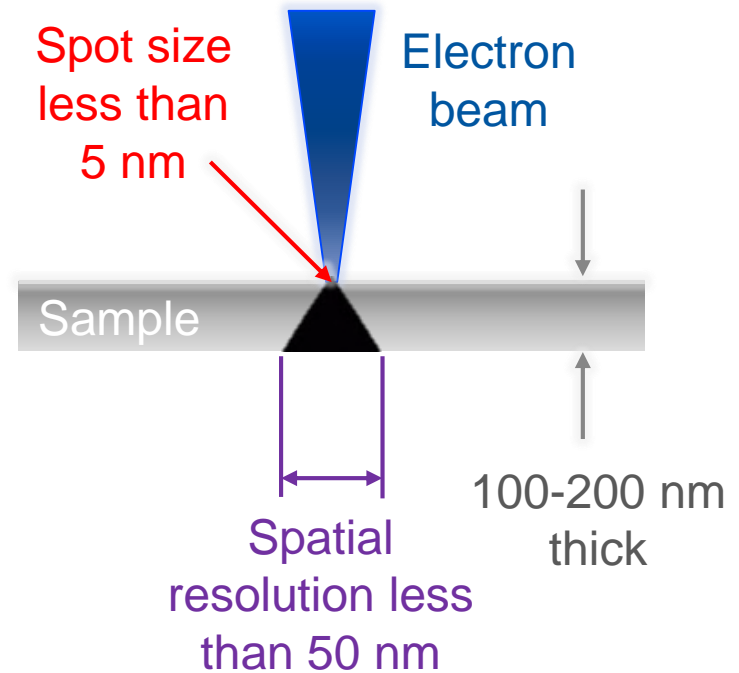
# High resolution elemental mapping

- Need to examine elemental diffusion
- Limiting factor on EDS resolution is interaction volume not beam spot size
- Resolution insufficient for thin film samples



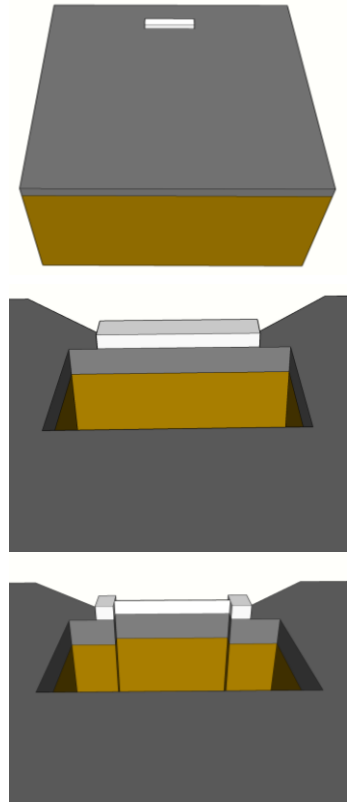
# Transmission EDS

- Improve resolution – reduce interaction volume
- Lamella 100-200 nm thick
- Nanoscale mapping possible
- Problem:
  - 10-20 hours milling time
  - Complex experimental process – prone to failure
  - Many samples need investigating



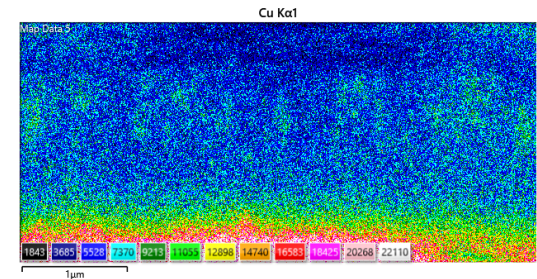
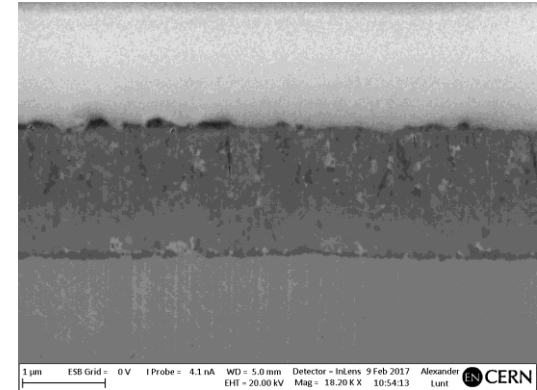
# Solution: 'Rapid' TEDS

- New approach based on 'in-situ' lamella
- No need for risky removal of lamella
- Significant reduction in milling time (4 hours)
- Similar nanoscale resolution EDS mapping possible.



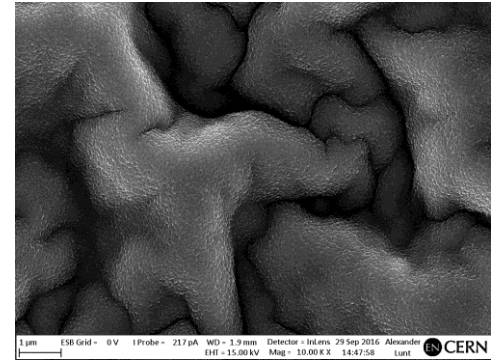
# Contamination assessment

- Electron contrast in cross sectional analysis
- The origins of this:
  - Phase segregation
  - Contamination
  - Electron channelling from grain orientation
- TEDS can provide answers



# Microscale residual stress analysis

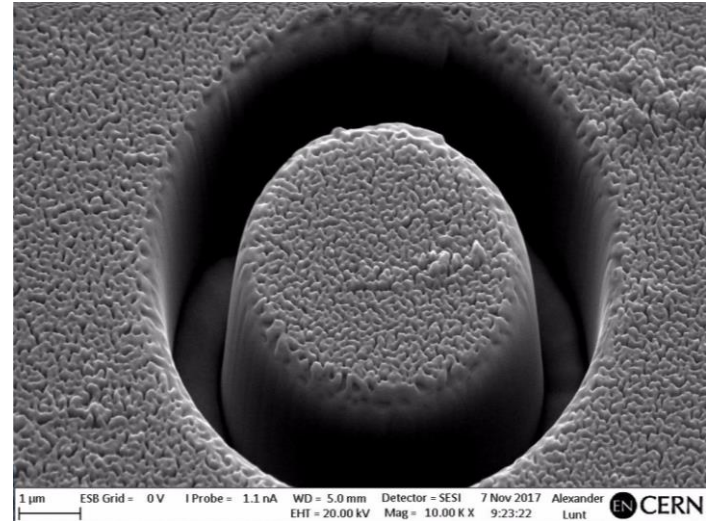
- Residual stress in thin films
  - Peel off &  $T_c$
- X-ray diffraction conventional approach
  - Average over large area
- Need to quantify at specific locations
  - origins of failure





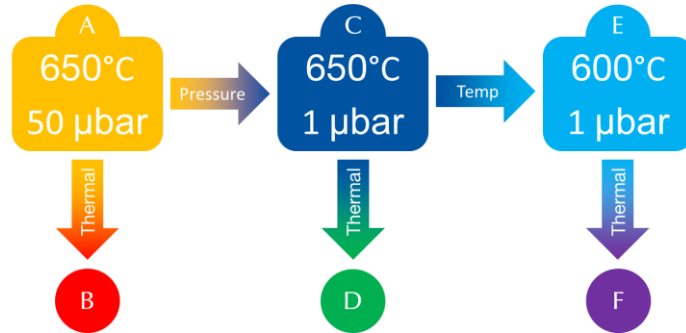
# Ring-core residual stress analysis

- FIB based technique
- Incremental annular milling
- Relaxation of core
- Record SEM images
- Quantification using digital image correlation
- Compare to finite element simulations
- Quantify residual stress originally present within core



# Nb<sub>3</sub>Sn thin films

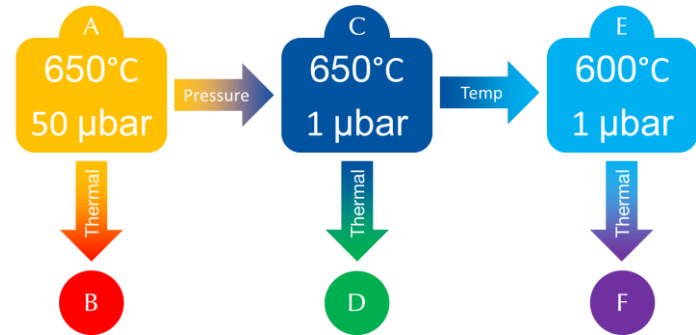
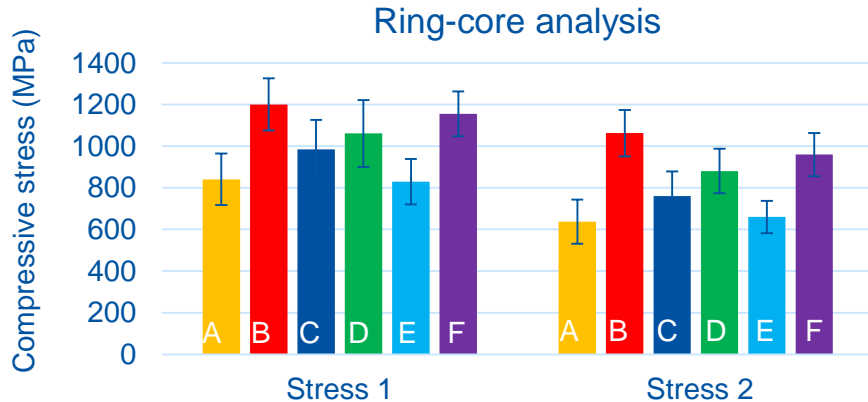
- Influence of coating pressure, temp and thermal processing



- Thermal treatment = 650°C for 5 hours
- High compressive stress = higher critical temperature

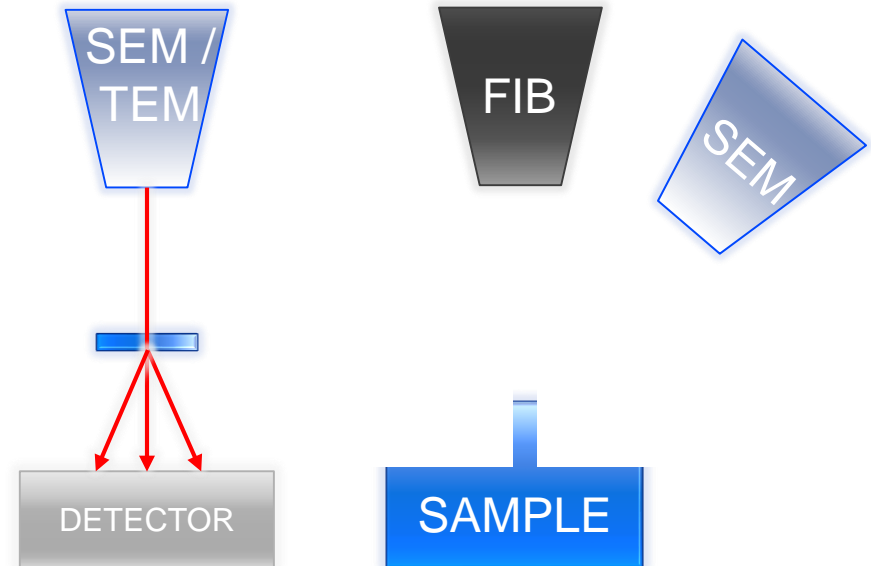
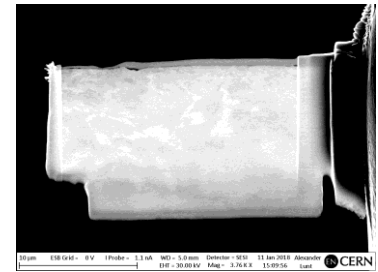
# Residual stress results

- Highly compressive stresses\*
- Lower temp + higher pressure – reduced stress
- Thermal treatment – increase in stress



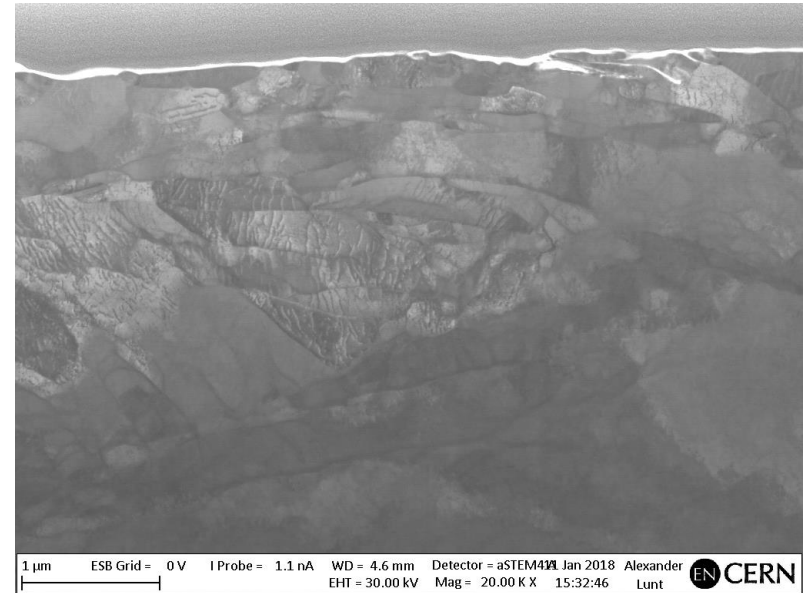
# Cavity substrate analysis

- Investigations into Cu cavity manufacturing techniques ongoing
  - Spinning and electro-hydraulic forming
- Scanning transmission electron microscopy
  - TEM lamella



# Potential insights

- Nanoscale behaviour
- Dislocation density
- Surface response
- Grain characteristics
- Comparison between inner & outer surfaces

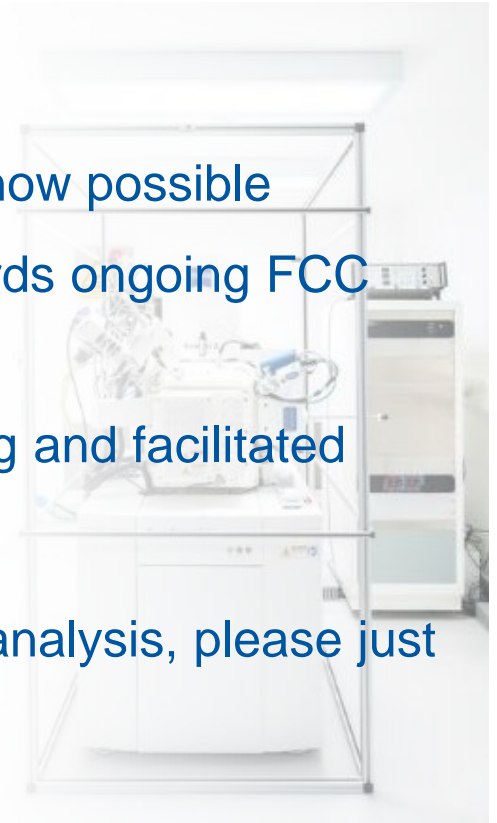


Further discussion – upcoming presentation  
Carolina Abajo Clemente 14:30 Berlage zaal (1.9)

# Summary

- Powerful tool with broad spectrum of techniques now possible
- Conventional & tailored techniques directed towards ongoing FCC projects
- Useful results which have improved understanding and facilitated design improvements

If you have any studies which may benefit from FIB analysis, please just get in touch!



# Any questions?



Email: *alexander.lunt@cern.ch*

Mobile: **16 10 86**

Office: **63 64 4 599/R-007**

FIB Lab: **63 11 1 376/R-014**

